PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company	STMicroelectronics International N.V
1.2 PCN No.	EMBEDDED PROCESSING/25/15833
1.3 Title of PCN	STM32MP15x - product enhancement
1.4 Product Category	STM32MP15x
1.5 Issue date	2025-10-23

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Patrick AIDOUNE
2.1.2 Marketing Manager	Veronique BARLATIER
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	**3.2 Type of change**	**3.3 Manufacturing Location**
General Product & Design	Die redesign : Mask or mask set change with new die design like metallization (specifically chip frontside) or bug fix	ST Crolles 300 (France)

4. Description of change

	Old	**New**
4.1 Description	Current STM32MP15x (Die 500 - cut2.1 - Revision Z) product has limitation : - Improper isolation of protected secure resources - Improper MCU resource isolation as described in Errata Sheet ES0438 - Revision 11 - September 2024.	New STM32MP15x (Die 500 - cut2.2 - Revision Y) product enhancement fixes those limitations: - Improper isolation of protected secure resources - Improper MCU resource isolation as described in Errata Sheet ES0438 - Revision 11.1 - October 2024.
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	Functionality enhancement	

5. Reason / motivation for change

5.1 Motivation	Improvements implemented to increase robustness, performances and quality of our products.
5.2 Customer Benefit	SERVICE CONTINUITY

6. Marking of parts / traceability of change

6.1 Description	Traceability ensured by ST internal tools. Die revision changes from "Z" to "Y" on Package Marking

7. Timing / schedule

7.1 Date of qualification results	2024-09-05
7.2 Intended start of delivery	2026-02-17
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	15833 MDG-MCD-RER1902 V3.0 - STM32MP15x - Die 500XXXY - Reliability evaluation report.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	**Issue Date**	2025-10-23

9. Attachments (additional documentations)

15833 Public product.pdf
15833 MDG-MCD-RER1902 V3.0 - STM32MP15x - Die 500XXXY - Reliability evaluation report.pdf
15833 _Additional information.pdf

10. Affected parts

10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	**10.1.2 Supplier Part No**	**10.1.2 Supplier Part No**
	STM32MP151AAA3	
	STM32MP151AAB3	
	STM32MP151AAC3	
	STM32MP151AAD3	
	STM32MP151CAA3	
	STM32MP151CAB3	
	STM32MP151CAC3	
	STM32MP151CAD3	
	STM32MP151DAB1	
	STM32MP151DAC1	
	STM32MP151DAD1	
	STM32MP153AAA3	
	STM32MP153AAB3	
	STM32MP153AAC3	
	STM32MP153AAD3	
	STM32MP153CAA3	
	STM32MP153CAB3	
	STM32MP153CAC3	
	STM32MP153CAD3	
	STM32MP153DAB1	
	STM32MP153DAD1	
	STM32MP157AAA3	
	STM32MP157AAB3	
	STM32MP157AAC3	
	STM32MP157AAD3	
	STM32MP157CAA3	
	STM32MP157CAB3	
	STM32MP157CAC3	
	STM32MP157CAD3	
	STM32MP157DAA1	
	STM32MP157DAB1	
	STM32MP157DAC1	
	STM32MP157DAD1	
	STM32MP157FAA1	
	STM32MP157FAB1	
	STM32MP157FAC1	
	STM32MP157FAD1	

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